



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kevin M. McHugh

Serial No.: 09/592,003

Filed: June 12, 2000

For: RAPID SOLIDIFICATION
PROCESSING FOR PRODUCING MOLDS,
DIES AND RELATED TOOLINGS

Examiner: Leyson

Group Art Unit: 1722

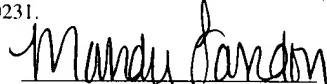
Attorney Docket No.: EGG-PI-612A1a

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PRELIMINARY AMENDMENT

The Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, please amend the application as follows: